

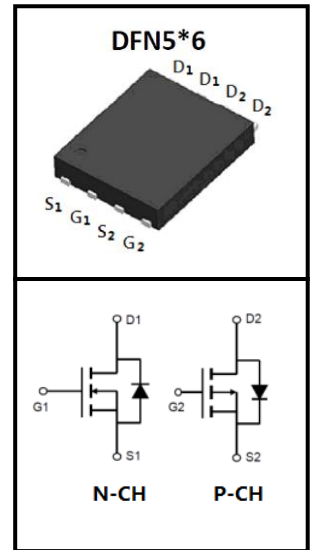
# N+P-Channel Logic Level Enhancement Mode Power MOSFET

## FEATURES

- Super Low Gate Charge
- 100% EAS Guaranteed
- RoHS compliant
- Green Device Available
- Excellent CdV/dt effect decline
- Advanced high cell density Trench technology

## APPLICATIONS

- H-bridge
- Inverters



## Device Marking and Package Information

Device	Package	Marking
CTN04PN035	DFN5*6	CTN04PN035

## Absolute Maximum Ratings at $T_j = 25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Value		Unit
Drain-Source Voltage ( $V_{GS} = 0V$ )	$V_{DSS}$	40	-40	V
Continuous Drain Current $T_C = 25^\circ\text{C}$ (note1)	$I_D$	18	-18	A
Continuous Drain Current $T_C = 100^\circ\text{C}$ (note1)		10	-9.5	
Pulsed Drain Current (note2)	$I_{DM}$	32	-26	A
Gate Source Voltage	$V_{GSS}$	$\pm 20$	$\pm 20$	V
Power Dissipation $T_C = 25^\circ\text{C}$ (note4)	$P_D$	10	20	W
Single Pulse Avalanche Energy (note3)	$E_{AS}$	12	25	mJ
Operating Junction and Storage Temperature Range	$T_J, T_{stg}$	-55~+175		$^\circ\text{C}$

## Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	40	$^\circ\text{C/W}$
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	65	$^\circ\text{C/W}$

**Electrical Characteristics  $T_j = 25^\circ\text{C}$  unless otherwise specified**

Parameter	Symbol	Test Conditions	Value			Unit
			Min.	Typ.	Max.	
<b>Static</b>						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	40	--	--	V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 32V, V_{GS} = 0V, T_J = 25^\circ\text{C}$	--	--	1	$\mu A$
		$V_{DS} = 32V, V_{GS} = 0V, T_J = 100^\circ\text{C}$	--	--	5	$\mu A$
Gate-Source Leakage	$I_{GSS}$	$V_{GS} = \pm 20V$	--	--	$\pm 100$	nA
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	1.2	--	2.5	V
Drain-Source On-Resistance (note2)	$R_{DS(on)}$	$V_{GS} = 10V, I_D = 15A$	--	15	20	$m\Omega$
		$V_{GS} = 4.5V, I_D = 10A$	--	17	23	$m\Omega$
<b>Dynamic</b>						
Input Capacitance	$C_{iss}$	$V_{GS} = 0V, V_{DS} = 15V, f = 1.0MHz$	--	415	--	pF
Output Capacitance	$C_{oss}$		--	112	--	
Reverse Transfer Capacitance	$C_{rss}$		--	11	--	
Total Gate Charge (4.5V)	$Q_g$	$V_{DS} = 30V, I_D = 4A, V_{GS} = 10V$	--	6.5	--	nC
Gate-Source Charge	$Q_{gs}$		--	1.2	--	
Gate-Drain Charge	$Q_{gd}$		--	1.1	--	
Turn-on Delay Time	$t_{d(on)}$	$V_{DS} = 15V, I_D = 4A, V_{GS} = 10V, R_G = 3.3\Omega$	--	4	--	ns
Turn-on Rise Time	$t_r$		--	3	--	
Turn-off Delay Time	$t_{d(off)}$		--	15	--	
Turn-off Fall Time	$t_f$		--	2	--	
<b>Body Diode Characteristics</b>						
Continuous Body Diode Current	$I_S$		--	--	18	A
Pulsed Diode Forward Current	$I_{SM}$		--	--	32	A
Body Diode Voltage	$V_{SD}$	$I_{SD} = 1A, V_{GS} = 0V$	--	--	1.2	V

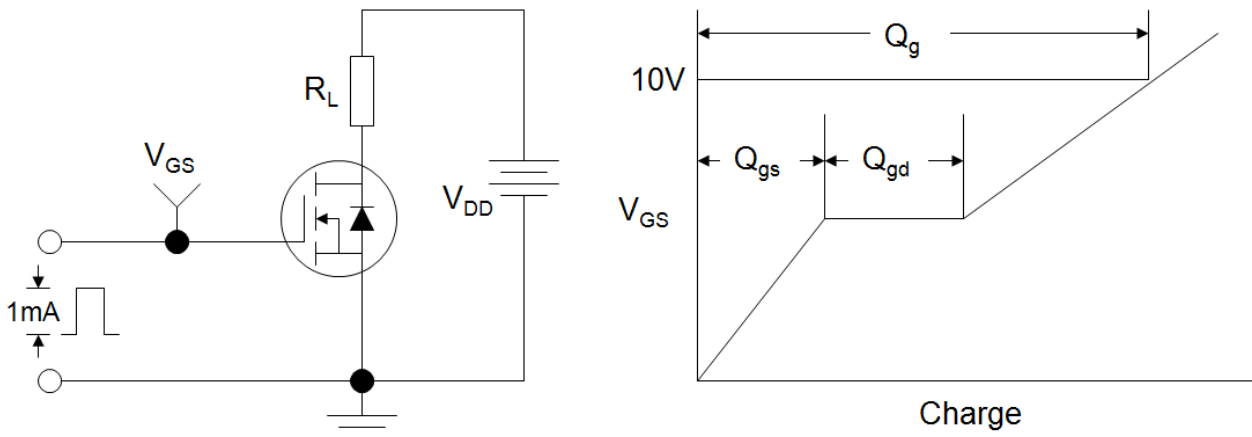
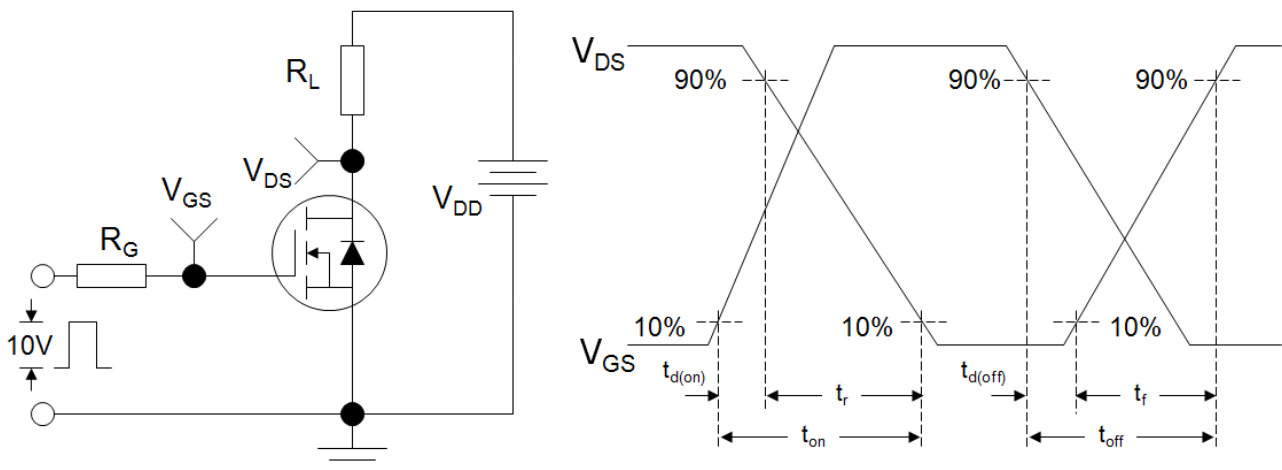
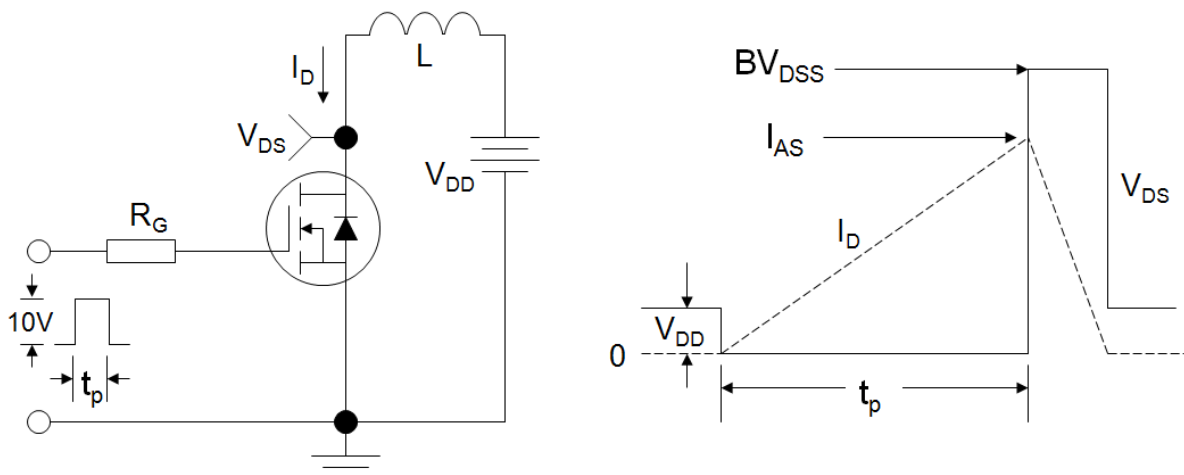
**Notes**

1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 20Z copper.
2. The data tested by pulsed , pulse width $\leq 300\mu s$  , duty cycle $\leq 2\%$
3. The EAS data shows Max. rating . The test condition is  $V_{DD} = 25V, V_{GS} = 10V, L = 0.1mH$
4. The power dissipation is limited by  $175^\circ\text{C}$  junction temperature
5. The data is theoretically the same as  $I_D$  and  $I_{DM}$  , in real applications , should be limited by total power dissipation.

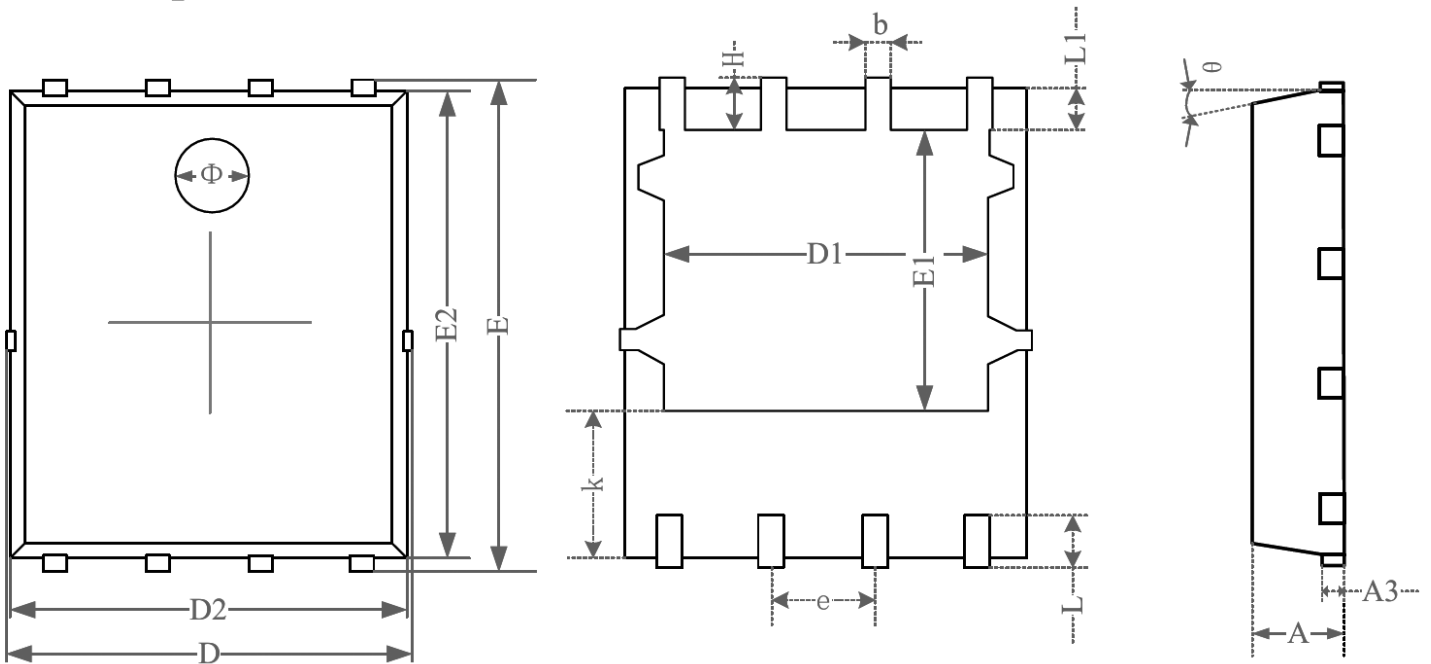
Electrical Characteristics $T_j = 25^\circ\text{C}$ unless otherwise specified						
Parameter	Symbol	Test Conditions	Value			Unit
			Min.	Typ.	Max.	
<b>Static</b>						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	-40	--	--	V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = -32V, V_{GS} = 0V, T_J = 25^\circ\text{C}$	--	--	1	$\mu A$
		$V_{DS} = -32V, V_{GS} = 0V, T_J = 100^\circ\text{C}$	--	--	5	$\mu A$
Gate-Source Leakage	$I_{GSS}$	$V_{GS} = \pm 20V$	--	--	$\pm 100$	nA
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = -250\mu A$	-1.2	--	-2.5	V
Drain-Source On-Resistance (note2)	$R_{DS(on)}$	$V_{GS} = -10V, I_D = -15A$	--	29	35	$m\Omega$
		$V_{GS} = -4.5V, I_D = -10A$	--	38.5	46	$m\Omega$
<b>Dynamic</b>						
Input Capacitance	$C_{iss}$	$V_{GS} = 0V,$ $V_{DS} = -15V,$ $f = 1.0MHz$	--	1040	--	pF
Output Capacitance	$C_{oss}$		--	180	--	
Reverse Transfer Capacitance	$C_{rss}$		--	125	--	
Total Gate Charge (4.5V)	$Q_g$	$V_{DS} = -30V, I_D = -4A,$ $V_{GS} = -10V$	--	19	--	nC
Gate-Source Charge	$Q_{gs}$		--	3.6	--	
Gate-Drain Charge	$Q_{gd}$		--	4.6	--	
Turn-on Delay Time	$t_{d(on)}$	$V_{DS} = -15V, I_D = -4A$ $V_{GS} = -10V, R_G = 3.3\Omega$	--	10	--	ns
Turn-on Rise Time	$t_r$		--	5.5	--	
Turn-off Delay Time	$t_{d(off)}$		--	3.6	--	
Turn-off Fall Time	$t_f$		--	4.6	--	
<b>Body Diode Characteristics</b>						
Continuous Body Diode Current	$I_S$		--	--	-18	A
Pulsed Diode Forward Current	$I_{SM}$		--	--	-26	A
Body Diode Voltage	$V_{SD}$	$I_{SD} = -1A, V_{GS} = 0V$	--	--	-1.2	V

**Notes**

1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
2. The data tested by pulsed , pulse width $\leq 300\mu s$  , duty cycle $\leq 2\%$
3. The EAS data shows Max. rating . The test condition is  $V_{DD} = 25V, V_{GS} = 10V, L = 0.1mH$
4. The power dissipation is limited by  $175^\circ\text{C}$  junction temperature
5. The data is theoretically the same as  $I_D$  and  $I_{DM}$  , in real applications , should be limited by total power dissipation.

**Figure A: Gate Charge Test Circuit and Waveform**

**Figure B: Resistive Switching Test Circuit and Waveform**

**Figure C: Unclamped Inductive Switching Test Circuit and Waveform**


# DFN5\*6



SYMBOLS	DIMENSIONS IN MILLIMETERS			DIMENSIONS IN INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.870	0.900	0.930	0.034	0.035	0.036
A3	0.152REF.			0.006REF.		
D	4.944	5.020	5.096	0.195	0.198	0.201
E	5.974	6.050	6.126	0.235	0.238	0.241
D1	3.910	4.010	4.110	0.154	0.158	0.162
E1	3.375	3.475	3.575	0.133	0.137	0.141
D2	4.870	4.900	4.930	0.192	0.193	0.194
E2	5.720	5.750	5.780	0.226	0.227	0.228
k	1.190	1.290	1.390	0.047	0.051	0.055
b	0.350	0.380	0.410	0.014	0.015	0.016
e	1.270TYP.			0.050TYP.		
L	0.559	0.635	0.711	0.022	0.025	0.028
L1	0.424	0.500	0.576	0.017	0.020	0.023
H	0.574	0.650	0.726	0.023	0.026	0.029
$\theta$	10°	11°	12°	10°	11°	12°
$\Phi$	1.150	1.200	1.250	0.045	0.047	0.049

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